

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT8348187

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the NAME OF THE SECOND ASSIGNEE previously recorded on Reel 052850 Frame 0237. Assignor(s) hereby confirms the DEED OF RELEASE.
CONVEYING PARTY DATA	
Name	Execution Date
CITICORP INTERNATIONAL LIMITED, AS COMMON SECURITY AGENT	05/03/2019
RECEIVING PARTY DATA	
Name:	STATS CHIPPAC, INC.
Street Address:	46429 LANDING PARKWAY
City:	FREMONT
State/Country:	CALIFORNIA
Postal Code:	94538
Name:	STATS CHIPPAC PTE. LTD.
Street Address:	5 YISHUN STREET 23
City:	SINGAPORE
State/Country:	SINGAPORE
Postal Code:	768442
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13523261
CORRESPONDENCE DATA	
Fax Number:	(949)391-4699
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	886223692800
Email:	usa@jcipgroup.com
Correspondent Name:	JCIPRNET
Address Line 1:	8F-1, NO. 100, ROOSEVELT RD. SEC. 2,
Address Line 4:	TAIPEI, TAIWAN 100404
ATTORNEY DOCKET NUMBER:	1725AS-2
NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	12/21/2023

Total Attachments: 31

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506093263 06/05/2020

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6139983

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST

CONVEYING PARTY DATA

Name	Execution Date
CITICORP INTERNATIONAL LIMITED, AS COMMON SECURITY AGENT	05/03/2019

RECEIVING PARTY DATA

Name:	STATS CHIPPAK, INC.
Street Address:	46429 LANDING PARKWAY
City:	FREMONT
State/Country:	CALIFORNIA
Postal Code:	94538
Name:	STATS CHIPPAK PTE. LTD. FORMERLY KNOWN AS STATS CHIPPAK LTD.
Street Address:	5 YISHUN STREET 23
City:	SINGAPORE
State/Country:	SINGAPORE
Postal Code:	768442

PROPERTY NUMBERS Total: 250

Property Type	Number
Patent Number:	8642469
Patent Number:	8642446
Patent Number:	8642384
Patent Number:	8642383
Patent Number:	8642382
Patent Number:	8642381
Patent Number:	8637974
Patent Number:	8637394
Patent Number:	8633586
Patent Number:	8633578
Patent Number:	8633100
Patent Number:	8633063
Patent Number:	8633062
Patent Number:	8633059
Patent Number:	8633058

PATENT

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REEL: 052850 FRAME: 0237

PATENT

REEL: 066125 FRAME: 0739

Property Type	Number
Patent Number:	8633056
Patent Number:	8632112
Patent Number:	8629567
Patent Number:	8629537
Patent Number:	8624402
Patent Number:	8624370
Patent Number:	8624364
Patent Number:	8623711
Patent Number:	8623708
Patent Number:	8618653
Patent Number:	8617933
Patent Number:	8617924
Patent Number:	8614508
Patent Number:	8609525
Patent Number:	8609463
Patent Number:	8604624
Patent Number:	8604602
Patent Number:	8604596
Patent Number:	8603859
Patent Number:	8598690
Patent Number:	8598034
Patent Number:	RE44608
Patent Number:	8592989
Patent Number:	8592975
Patent Number:	8592950
Patent Number:	8592311
Patent Number:	8592286
Patent Number:	8587098
Patent Number:	8586422
Patent Number:	8581382
Patent Number:	8581380
Patent Number:	8581375
Patent Number:	RE44579
Patent Number:	8574964
Patent Number:	8574959
Patent Number:	RE44562
Patent Number:	8569895
Patent Number:	8569882

PATENT

REEL: 052850 FRAME: 0238

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REEL: 066125 FRAME: 0740

Property Type	Number
Patent Number:	8569872
Patent Number:	8569870
Patent Number:	8569869
Patent Number:	8569112
Patent Number:	8564125
Patent Number:	8563418
Patent Number:	8559185
Patent Number:	8558378
Patent Number:	8558369
Patent Number:	8558366
Patent Number:	8557639
Patent Number:	8557638
Patent Number:	RE44524
Patent Number:	8546957
Patent Number:	8546929
Patent Number:	8546194
Patent Number:	8546189
Patent Number:	8541886
Patent Number:	8541872
Patent Number:	RE44500
Patent Number:	8536718
Patent Number:	8536692
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Patent Number:	8536689
Patent Number:	8536688
Patent Number:	8535981
Patent Number:	8531043
Patent Number:	8531012
Patent Number:	8530280
Patent Number:	8530277
Patent Number:	8530274
Patent Number:	8525350
Patent Number:	8525337
Patent Number:	8525325
Patent Number:	8524538
Patent Number:	8524537
Patent Number:	8519536
Patent Number:	8519518

PATENT

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REEL: 066125 FRAME: 0741

Property Type	Number
Patent Number:	8519517
Patent Number:	8518822
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Patent Number:	8518749
Patent Number:	8513812
Patent Number:	8513801
Patent Number:	8513788
Patent Number:	8513542
Patent Number:	8513057
Patent Number:	RE44438
Patent Number:	RE44431
Patent Number:	8508026
Patent Number:	8507319
Patent Number:	8502392
Patent Number:	8502391
Patent Number:	8502387
Patent Number:	8502371
Patent Number:	8502358
Patent Number:	8502357
Patent Number:	8502352
Patent Number:	8502339
Patent Number:	8501618
Patent Number:	8501544
Patent Number:	8501541
Patent Number:	8501540
Patent Number:	8501535
Patent Number:	8497575
Patent Number:	8493748
Patent Number:	8492888
Patent Number:	8492887
Patent Number:	8492204
Patent Number:	8492203
Patent Number:	8492201
Patent Number:	8492197
Patent Number:	RE44377
Patent Number:	8487434
Patent Number:	RE44355
Patent Number:	8482115

PATENT

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PATENT

REEL: 066125 FRAME: 0742

Property Type	Number
Patent Number:	8481420
Patent Number:	8481371
Patent Number:	8476775
Patent Number:	8476772
Patent Number:	8476761
Patent Number:	8476135
Patent Number:	8476120
Patent Number:	8476115
Patent Number:	8476111
Patent Number:	8471394
Patent Number:	8471374
Patent Number:	8466567
Patent Number:	8466057
Patent Number:	8461680
Patent Number:	8460968
Patent Number:	8455993
Patent Number:	8455991
Patent Number:	8455988
Patent Number:	8445990
Patent Number:	8445323
Patent Number:	8435835
Patent Number:	8432028
Patent Number:	8432026
Patent Number:	8426955
Patent Number:	8422243
Patent Number:	8421221
Patent Number:	8421210
Patent Number:	8421203
Patent Number:	8421202
Patent Number:	8421201
Patent Number:	8421198
Patent Number:	8421197
Patent Number:	8420950
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Patent Number:	8420448
Patent Number:	8420447
Patent Number:	8415810
Patent Number:	8415786

PATENT

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PATENT

REEL: 066125 FRAME: 0743

Property Type	Number
Patent Number:	8415778
Patent Number:	8415206
Patent Number:	8415205
Patent Number:	8415204
Patent Number:	8410596
Patent Number:	8410594
Patent Number:	8410587
Patent Number:	8409979
Patent Number:	8409978
Patent Number:	8409926
Patent Number:	8409923
Patent Number:	8409921
Patent Number:	8409920
Patent Number:	8409918
Patent Number:	8409917
Patent Number:	8406004
Patent Number:	8405230
Patent Number:	8405197
Patent Number:	8404524
Patent Number:	8404518
Patent Number:	8399968
Patent Number:	8399306
Patent Number:	8399305
Patent Number:	8399300
Patent Number:	8395254
Patent Number:	8395251
Patent Number:	8395053
Patent Number:	8390110
Patent Number:	8390108
Patent Number:	8389398
Patent Number:	8389332
Patent Number:	8389330
Patent Number:	8389329
Patent Number:	8384227
Patent Number:	8383458
Patent Number:	8378502
Patent Number:	8378477
Patent Number:	8378476

PATENT

REEL: 052850 FRAME: 0242

PATENT

REEL: 066125 FRAME: 0744

Property Type	Number
Patent Number:	8377750
Patent Number:	8375576
Patent Number:	8372695
Patent Number:	8368200
Patent Number:	8368199
Patent Number:	8368188
Patent Number:	8368187
Patent Number:	8367480
Patent Number:	8367470
Patent Number:	8367467
Patent Number:	8367465
Patent Number:	8362601
Patent Number:	8354746
Patent Number:	8354742
Patent Number:	8350384
Patent Number:	8350368
Patent Number:	8349735
Patent Number:	8349721
Patent Number:	8349657
Patent Number:	8344495
Patent Number:	8338233
Patent Number:	8334601
Patent Number:	8334584
Patent Number:	8334171
Patent Number:	8334169
Patent Number:	8334150
Patent Number:	8329554
Patent Number:	8318539
Patent Number:	8318537
Patent Number:	8314486
Patent Number:	8310058
Patent Number:	8310038
Patent Number:	8309397
Patent Number:	8304922
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Patent Number:	8304919
Patent Number:	8304900
Patent Number:	8304898

PATENT

REEL: 052850 FRAME: 0243

PATENT

REEL: 066125 FRAME: 0745

Property Type	Number
Patent Number:	8304880
Patent Number:	8304874
Patent Number:	8304869
Patent Number:	8304337
Patent Number:	8304296
Patent Number:	8304286
Patent Number:	8304277

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 4804999400

Email: main@plgaz.com

Correspondent Name: PATENT LAW GROUP: ATKINS AND ASSOCIATES

Address Line 1: 123 W. CHANDLER HEIGHTS ROAD, #12535

Address Line 4: CHANDLER, ARIZONA 85248

ATTORNEY DOCKET NUMBER:	2515.5050
NAME OF SUBMITTER:	MARITZA O'NEILL
SIGNATURE:	/MARITZA O'NEILL/
DATE SIGNED:	06/05/2020

Total Attachments: 22

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PATENT
REEL: 066125 FRAME: 0746

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REEL: 066125 FRAME: 0747

3 May 2019

CITICORP INTERNATIONAL LIMITED

and

CITIBANK KOREA INC.

and

DBS BANK LTD.

and

THE BANK OF NEW YORK MELLON

and

The Companies listed in Schedule 1

DEED OF RELEASE

LATHAM & WATKINS

9 Raffles Place #42-02

Republic Plaza

Singapore 048619

Tel: +65 6539 1161

www.lw.com

THIS DEED is made on 3 May 2019

BETWEEN:

- (1) **CITICORP INTERNATIONAL LIMITED** as common security agent for the Secured Parties (as defined in the Released Documents defined below) (the “**Common Security Agent**”);
- (2) **CITIBANK KOREA INC.** as Korean security agent for the Secured Parties (as defined in the Released Documents defined below) (the “**Korean Security Agent**”, and together with the Common Security Agent, the “**Security Agents**”);
- (3) **DBS BANK LTD.** as facility agent for the Finance Parties (as defined in the Facilities Agreement defined below) (the “**Facility Agent**”);
- (4) **THE BANK OF NEW YORK MELLON** as trustee for the Holders (as defined in the Indenture defined below) (the “**Trustee**”); and
- (5) **THE ENTITIES** listed in Schedule 1 (*Chargors*) (the “**Chargors**”)

WHEREAS:

- (A) The Chargors, the Facility Agent, the Trustee and the Security Agents enter into this Deed in connection with the Facilities Agreement (as defined below) and the Indenture (as defined below), pursuant to the terms of which certain credit facilities were made available to the Chargors.
- (B) Pursuant to the terms of the Facilities Agreement and the Indenture, the Chargors have given certain guarantees and security pursuant to each of the documents listed in Schedule 2 (*Released Documents*) (the “**Released Documents**”).
- (C) The Chargors have requested that the Security Agents release and discharge the guarantees and security created by or pursuant to the Released Documents on the terms set out in this Deed.

IT IS AGREED as follows:

1. DEFINITIONS

1.1 In this Deed:

“**Facilities Agreement**” means the senior term loan and revolving credit facilities agreement dated 12 April 2016 between, among others, STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.), as borrower, and DBS Bank Ltd., as facility agent, under which certain lenders have made available a US\$315,000,000 facility to STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.) and certain of its subsidiaries;

“**Indenture**” means the indenture dated as of 24 November 2015 among STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.), as issuer, and The Bank of New York Mellon, as trustee, providing for the issuance of 8.5% senior secured notes due 2020 in an aggregate principal amount of US\$425,000,000; and

“**Intercreditor Deed**” means the intercreditor deed dated 6 August 2015 between, among others, STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.), DBS Bank Ltd., The Bank of New York Mellon, Citicorp International Limited and Citibank Korea Inc.

1.2 Terms defined in the Facilities Agreement, the Indenture and the Intercreditor Deed shall have the same meaning when used in this Deed unless a contrary indication appears herein.

2. RELEASE AND DISCHARGE

2.1 In consideration of and conditional upon receipt by the Security Agents of all monies owed to the Senior Creditors pursuant to the Senior Finance Documents, the Security Agents, the Facility Agent and the Trustee hereby irrevocably and unconditionally:

- (a) releases and discharges the Chargors from all present or future, actual or contingent liabilities, obligations, covenants, undertakings, guarantees and security created, evidenced or conferred by, and all rights, claims, actions, suit, accounts, damages and demands whatsoever, known or unknown, arising under, the Released Documents;
- (b) reassigns and retransfers to the Chargors all rights, interest and title to all assets and property of the relevant Chargor which were assigned or transferred to the Security Agents by or pursuant to the Released Documents;
- (c) authorises each Chargor to give notice (at that Chargor's cost and expense) on behalf of the Security Agents of the releases under this Deed to any person on whom notice of any security interest created by the Released Documents was served; and
- (d) agrees that it will, immediately following such release, return any share certificates, stock transfer forms and other documents of title held by it in relation to the Released Documents to the Chargors (or as they may otherwise direct).

3. EXPENSES

Each Chargor shall within three Business Days of demand, pay to each of the Security Agents, the Facility Agent and the Trustee the amount of all costs and expenses (including legal fees) incurred by it or by any Receiver appointed by it under the Released Documents in connection with the negotiation, preparation, execution and performance of this Deed.

4. FURTHER ASSURANCE

The Security Agents, the Facility Agent and the Trustee will, at the request and cost of any Chargor, do all such things and enter into and execute all such deeds, documents, memoranda, agreements or instruments as may be reasonably necessary to give effect to the provisions of this Deed.

5. MISCELLANEOUS

- 5.1 The Contracts (Rights of Third Parties) Act 1999 shall not apply to this Deed and no rights or benefits expressly or impliedly conferred by this Deed shall be enforceable under that Act against the parties to this Deed by any other person.
- 5.2 If any provision of this Deed is or becomes invalid, illegal or unenforceable in any respect under any law, the validity, legality and enforceability of the remaining provisions shall not be affected or impaired in any way.
- 5.3 This Deed may be executed in any number of counterparts, and this has the same effect as if the signatures on the counterparts were on a single copy of this Deed.
- 5.4 Failure by one or more parties ("Non-Signatories") to execute this Deed on the date hereof will not invalidate the provisions of this Deed as between the other Parties who do execute this Deed. Such Non-Signatories may execute this Deed on a subsequent date and will thereupon become bound by its provisions.

6. GOVERNING LAW AND JURISDICTION

- 6.1 This Deed and any non-contractual claims arising out of or in connection with it shall be governed by and construed in accordance with English law.
- 6.2 Subject to Clause 6.3 below, the Parties agree that the courts of England shall have exclusive jurisdiction to settle any dispute arising out of or in connection with this Deed, whether contractual or non-contractual (including a dispute regarding the existence, validity or termination of this Deed) (a “**Dispute**”). The Parties agree that the courts of England are the most appropriate and convenient courts to settle Disputes and accordingly no party will argue to the contrary.
- 6.3 The Parties agree that, for the benefit of the Secured Parties only, nothing in this Deed shall limit the right of the Senior Creditors to bring any legal action against any of the Chargors in any other court of competent jurisdiction.

IN WITNESS whereof this Deed has been duly executed as a deed and is delivered on the date stated at the beginning of this Deed.

SCHEDULE 1

RELEASED CHARGORS

Company name	Jurisdiction of incorporation
STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.)	Singapore
STATS ChipPAC (Barbados) Ltd	Barbados
ChipPAC International Company Limited	British Virgin Islands
STATS ChipPAC (BVI) Limited	British Virgin Islands
STATS ChipPAC Korea Limited	Korea
STATS ChipPAC, Inc.	Delaware, United States of America
Ong Meng Hwee	Singapore
Tan Lay Koon	Singapore
Woo Kwek Kiong	Singapore
Jiangsu Changjiang Electronics Technology Co., Ltd.	People's Republic of China

SCHEDULE 2

RELEASED DOCUMENTS

1. the facility agreement dated 12 April 2016 between STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.), STATS ChipPAC (Barbados) Ltd, ChipPAC International Company Limited, STATS ChipPAC (BVI) Limited, STATS ChipPAC Korea Limited, STATS ChipPAC, Inc., DBS Bank Ltd., Barclays Bank PLC, ING Bank N.V., Singapore Branch, Taishin International Bank Co., Ltd, Singapore Branch, China Minsheng Banking Corp., Ltd., Hong Kong Branch, First Gulf Bank PJSC, Singapore Branch, KGI Bank and China CITIC Bank International Limited
2. the subsidiary guarantee agreement dated as of 24 November 2015 between STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.), STATS ChipPAC, Inc., ChipPAC International Company Limited, STATS ChipPAC (Barbados) Ltd, STATS ChipPAC (BVI) Limited, STATS ChipPAC Malaysia Sdn. Bhd., STATS ChipPAC Korea Ltd. and The Bank of New York Mellon
3. the debenture dated 6 August 2015 between STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.) and Citicorp International Limited
4. the debenture dated 6 August 2015 between STATS ChipPAC (Barbados) Ltd and Citicorp International Limited
5. the debenture dated 6 August 2015 between STATS ChipPAC (BVI) Limited, ChipPAC International Company Limited and Citicorp International Limited
6. the security agreement dated 6 August 2015 between STATS ChipPAC, Inc. and Citicorp International Limited
7. the share charge dated 6 August 2015 between STATS ChipPAC (BVI) Limited and Citicorp International Limited in respect of shares in STATS ChipPAC Malaysia Sdn. Bhd.
8. the equitable mortgage dated 6 August 2015 between STATS ChipPAC (Barbados) Ltd and Citicorp International Limited in respect of shares in STATS ChipPAC (BVI) Limited
9. the equitable mortgage dated 6 August 2015 between STATS ChipPAC, Inc. and Citicorp International Limited in respect of shares in ChipPAC International Company Limited
10. the share pledge dated 6 August 2015 between STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.) and Citicorp International Limited in respect of shares in STATS ChipPAC, Inc.
11. the unit pledge dated 6 August 2015 between STATS ChipPAC (BVI) Limited, STATS ChipPAC (Barbados) Ltd and Citicorp International Limited in respect of shares in STATS ChipPAC Korea Limited
12. the share pledge dated 6 August 2015 between STATS ChipPAC, Inc. and Citicorp International Limited in respect of shares in STATS ChipPAC (Barbados) Ltd
13. the share pledge dated 6 August 2015 between (among others) STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.), Tan Lay Koon and Citicorp International Limited in respect of shares in STATS ChipPAC (Thailand) Limited
14. the supplemental share pledge dated 23 November 2015 between Woo Kwek Kiong and Citicorp International Limited in respect of shares in STATS ChipPAC (Thailand) Limited

15. the share pledge dated 6 August 2015 between (among others) STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.), Ong Meng Hwee and Citicorp International Limited in respect of shares in STATS ChipPAC Services (Thailand) Limited
16. the supplemental share pledge dated 23 November 2015 between Woo Kwek Kiong and Citicorp International Limited in respect of shares in STATS ChipPAC Services (Thailand) Limited
17. the mortgage dated 6 August 2015 between STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.) and Citicorp International Limited
18. the patent security assignment dated 6 August 2015 between STATS ChipPAC, Inc., STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.) and Citicorp International Limited
19. the supplemental patent security agreement dated 1 October 2015 between STATS ChipPAC, Inc., STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.) and Citicorp International Limited
20. the trademark security assignment dated 6 August 2015 between STATS ChipPAC, Inc., STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.) and Citicorp International Limited
21. the copyright security assignment dated 1 October 2015 between STATS ChipPAC, Inc. and Citicorp International Limited
22. the deposit account control agreement dated 6 August 2015 between STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.), the Bank of America, N.A. and Citicorp International Limited
23. the deposit account control agreement dated 6 August 2015 between ChipPAC International Company Limited, Wells Fargo Bank, National Association and Citicorp International Limited
24. the deposit account control agreement dated 6 August 2015 between STATS ChipPAC (Barbados) Ltd, Wells Fargo Bank, National Association and Citicorp International Limited
25. the deposit account control agreement dated 6 August 2015 between STATS ChipPAC (BVI) Limited, Wells Fargo Bank, National Association and Citicorp International Limited
26. the deposit account control agreement dated 6 August 2015 between STATS ChipPAC (BVI) Limited, HSBC Bank USA, National Association and Citicorp International Limited
27. the deposit account and sweep investment control agreement dated 6 August 2015 between STATS ChipPAC, Inc., Wells Fargo Bank, National Association and Citicorp International Limited in respect of account number 436-9561246 and account number 429-6905987
28. the deposit account control agreement dated 6 August 2015 between STATS ChipPAC, Inc., HSBC Bank USA, National Association and Citicorp International Limited
29. the accounts security agreement dated 6 August 2015 between STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.) and Citicorp International Limited
30. the accounts security agreement dated 6 August 2015 between ChipPAC International Company Limited and Citicorp International Limited

31. the accounts security agreement dated 6 August 2015 between STATS ChipPAC (BVI) Limited and Citicorp International Limited
32. the accounts security agreement dated 6 August 2015 between STATS ChipPAC (Barbados) Ltd and Citicorp International Limited
33. the account pledge dated 6 August 2015 between STATS ChipPAC (BVI) Limited and Citibank Korea Inc. in respect of bank accounts in the Republic of Korea
34. the account pledge dated 6 August 2015 between STATS ChipPAC Korea Limited and Citibank Korea Inc. in respect of bank accounts in the Republic of Korea
35. the supplemental agreement dated 5 February 2016 between STATS ChipPAC Korea Limited and Citibank Korea Inc.
36. the supplemental agreement dated 5 February 2016 between STATS ChipPAC (BVI) Limited and Citibank Korea Inc.
37. the account charge dated 1 October 2015 between STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.) and Citicorp International Limited
38. the equipment yangdo-dambo agreement dated 18 April 2016 between STATS ChipPAC Korea Limited and Citibank Korea Inc.
39. the inventory yangdo-dambo agreement dated 12 April 2016 between STATS ChipPAC Korea Limited and Citibank Korea Inc.
40. the receivables assignment agreement dated 12 April 2016 between STATS ChipPAC Korea Limited and Citibank Korea Inc.
41. the insurance assignment agreement dated 12 April 2016 between STATS ChipPAC Korea Limited and Citibank Korea Inc.
42. the intellectual property kun-pledge agreement dated 12 April 2016 between STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.) and Citibank Korea Inc.
43. the intellectual property kun-pledge agreement dated 12 April 2016 between STATS ChipPAC, Inc. and Citibank Korea Inc.
44. the factory kun-mortgage agreement dated 12 April 2016 between STATS ChipPAC Korea Limited and Citibank Korea Inc.
45. the security provider confirmation deed dated 12 April 2016 between STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.), STATS ChipPAC (Barbados) Ltd, ChipPAC International Company Limited, STATS ChipPAC (BVI) Limited, STATS ChipPAC Korea Limited, STATS ChipPAC, Inc., Ong Meng Hwee, Tan Lay Koon and Woo Kwek Kiong
46. the JCET Refinancing Letter of Support dated 12 April 2016 between Jiangsu Changjiang Electronics Technology Co., Ltd., STATS ChipPAC Pte. Ltd. (formerly known as STATS ChipPAC Ltd.) and DBS Bank Ltd.
47. the JCET PERP Refinancing Undertaking dated 6 August 2015 between Jiangsu Changjiang Electronics Technology Co., Ltd. and Citicorp International Limited
48. the JCET Financing Letter of Support dated 22 August 2016 between Jiangsu Changjiang Electronics Technology Co., Ltd., STATS ChipPAC Pte. Ltd. and DBS Bank Ltd.

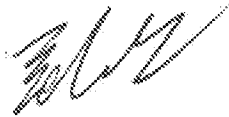
49. the JCET Financing Undertaking dated 29 November 2016 between Jiangsu Changjiang Electronics Technology Co., Ltd, STATS ChipPAC Pte. Ltd., and DBS Bank Ltd.
50. the JCET Refinancing Undertaking dated 8 September 2016 between Jiangsu Changjiang Electronics Technology Co., Ltd, STATS ChipPAC Pte. Ltd. and DBS Bank Ltd.

SIGNATORIES TO DEED OF RELEASE

THE COMMON SECURITY AGENT

EXECUTED as a DEED for and on behalf of

CITICORP INTERNATIONAL LIMITED

Name: Edmond Pang
Assistant Vice President 

Title: _____ Authorised Signatory

[Signature page to Deed of Release]

THE KOREAN SECURITY AGENT
EXECUTED as a DEED for and on behalf of
CITIBANK KOREA INC.

Citibank Korea Inc.
CEO Jin Hei Park
Name: _____
(Da-jong), 21 Cheonggyecheon-ro
Title: _____ Jung-gu, Seoul, 100-100 Korea
Authorized Signatory

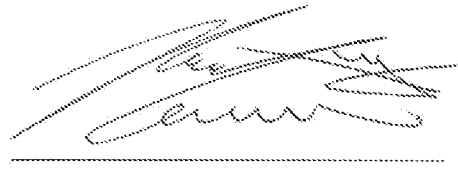


[Signature page to Deed of Release]

THE FACILITY AGENT

SIGNED, SEALED AND DELIVERED by

Name: Loy Hwee Chuan
Title: Senior Vice President

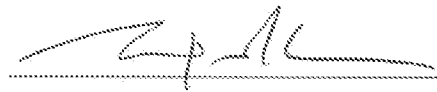


Authorised Signatory

as attorney for and on behalf of
DBS BANK LTD.

In the presence of

Name: TITUS NAM
NRIC / S8903575Z
Passport
No:



Signature of witness

[Signature page to Deed of Release]

THE TRUSTEE

EXECUTED as a DEED by

THE BANK OF NEW YORK MELLON,

LARISSA G. LAMBINO
Vice President

Name: _____



Title: _____

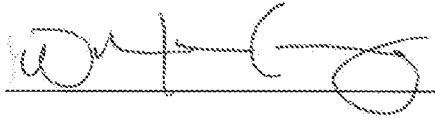
Authorised Signatory

[Signature page to Deed of Release]

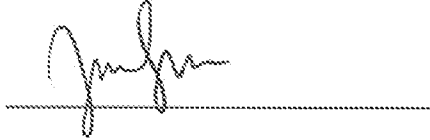
PATENT
REEL: 066125 FRAME: 0760

THE CHARGORS

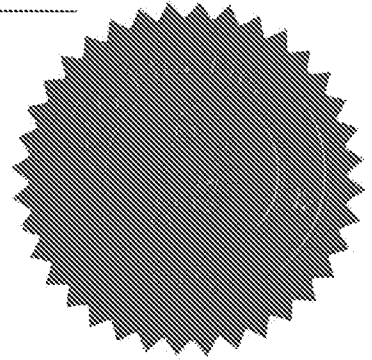
EXECUTED as a **DEED** by
STATS CHIPPAK PTE. LTD. (formerly known as **STATS CHIPPAK LTD.**)



Director



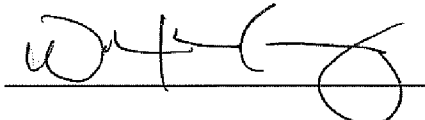
Director / Secretary



[Signature page to Deed of Release]

THE CHARGORS

EXECUTED as a DEED by
CHIPPAC INTERNATIONAL COMPANY LIMITED
a company incorporated in the British Virgin Islands, acting by


Name: Woo Kwok Kiong 
Title: Director Authorised Signatory

who, in accordance with the laws of that territory, are acting under the authority of that company

[Signature page to Deed of Release]

THE CHARGORS

EXECUTED as a **DEED** by
STATS CHIPPAC (BVI) LIMITED
a company incorporated in the British Virgin Islands, acting by

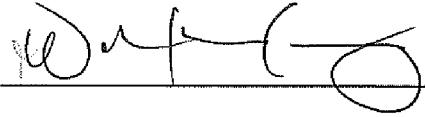
Name: Woo Kwok Kiong 
Title: Director Authorised Signatory

who, in accordance with the laws of that territory, are acting under the authority of that company

[Signature page to Deed of Release]

THE CHARGORS

EXECUTED as a DEED by
STATS CHIPPAC KOREA LIMITED
a company incorporated in Korea, acting by

Name: Woo Kwek Kiong 
Title: Authorized officer Authorized Signatory

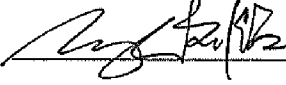
who, in accordance with the laws of that territory, are acting under the authority of that company

[Signature page to Deed of Release]

THE CHARGORS

**EXECUTED as a DEED by
STATS CHIPPAC, INC.**

a company incorporated in the United States of America, acting by

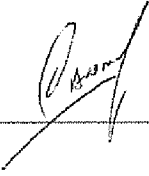
Name: MING LIU  _____
Title: DIRECTOR _____ Authorised Signatory

who, in accordance with the laws of that territory, are acting under the authority of that company

[Signature page to Deed of Release]

THE CHARGORS


**EXECUTED as a DEED by
ONG MENG HWEE**



in the presence of:

Name: Huang Yan

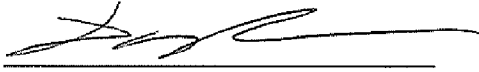
Address: (a) Meng Mo Kio St 65
#104-08/09, S(569054)



(Signature of witness)

THE CHARGORS

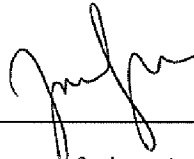
**EXECUTED as a DEED by
TAN LAY KOON**



in the presence of:

Name: *Joanne Shuck*

Address: *10 Ang Mo Kio St. 65*
#04-08/09, S(569059)



(Signature of witness)

[Signature page to Deed of Release]

THE CHARGORS

**EXECUTED as a DEED by
WOO KWEK KIONG**




A handwritten signature in black ink, appearing to read 'Woo Kwek Kiong', written over a horizontal line.

in the presence of:

Name: Joanne Shuck

Address: 10 Ang Mo Kio St. 65
#04-08/09, S(5691059)



A handwritten signature in black ink, written over a horizontal line.

(Signature of witness)

[Signature page to Deed of Release]

EXECUTED as a **DEED** by
JIANGSU CHANGJIANG ELECTRONICS TECHNOLOGY CO., LTD.
a company incorporated in the People's Republic of China, acting by

Name:  _____

Title: CHAIRMAN _____ Authorised Signatory

who, in accordance with the laws of that territory, are acting under the authority of that company

[Signature page to Deed of Release]